

2-Line Ultra Low Capacitance TVS Diode Array

Features

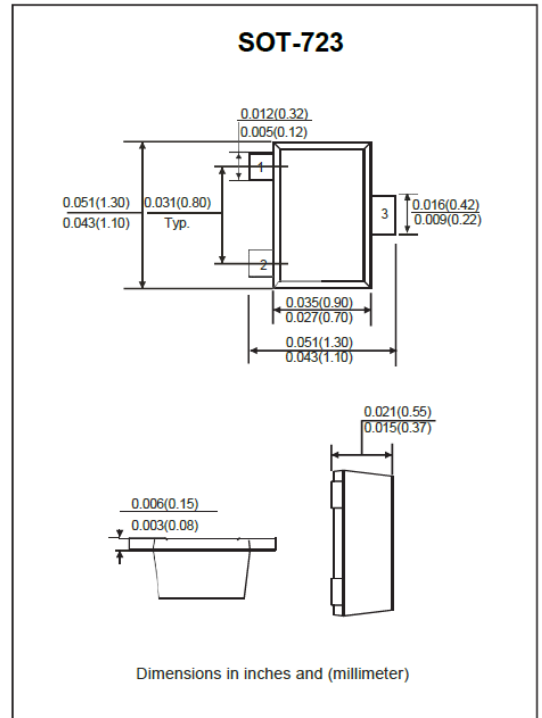
- IEC 61000-4-2 (ESD) $\pm 30\text{kV}$ (air), $\pm 30\text{kV}$ (contact)
- IEC 61000-4-4 (EFT) 40A (5/50ns)
- IEC 61000-4-5 (Lightning) 5A (8/20 μs)
- Ultra low Capacitance
- Low leakage current
- Low clamping voltage
- Operating voltage: 5V
- Protects one bidirectional line or two unidirectional lines

Applications

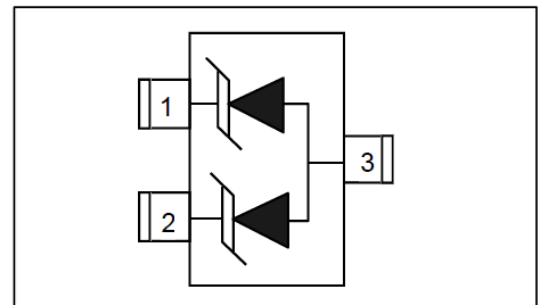
- Mobile Display Digital Interface (MDDI)
- InfiniBand Transceiver Protection
- Photodetector Protection
- Industrial Controls
- Server and Desktop PC

Mechanical Characteristics

- Package: SOT-723
- Lead Finish: Matte Tin
- Case Material: "Green" Molding Compound.
- Moisture Sensitivity: Level 3 per J-STD-020
- Material: RoHS compliant



Circuit and Pin Schematic



Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ Unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak Pulse Power ($t_p = 8/20\mu\text{s}$)	P_{PP}	55	W
Peak Pulse Current ($t_p = 8/20\mu\text{s}$)	I_{PP}	5	A
ESD per IEC 61000-4-2 (Air)	V_{ESD}	± 30	KV
ESD per IEC 61000-4-2 (Contact)		± 30	KV
Lead Soldering Temperature	T_L	260 (10 sec.)	$^\circ\text{C}$
Operating Temperature Range	T_J	-55 to + 125	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55 to + 150	$^\circ\text{C}$

Electrical Parameters (T _A = 25°C Unless otherwise noted)	
Symbol	Parameter
I _{PP}	Reverse Peak Pulse Current
V _C	Clamping Voltage @ I _{PP}
V _{RWM}	Reverse Stand-Off Voltage
I _R	Reverse Leakage Current @ V _{RWM}
V _{BR}	Breakdown Voltage @ I _T
I _T	Test Current
I _F	Forward Current
V _F	Forward Voltage @ I _F

Electrical Characteristics (T _A = 25°C Unless otherwise noted)						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Reverse Stand-Off Voltage	V _{RWM}	Pin 1 or Pin 2 to Pin 3			5	V
Reverse breakdown Voltage	V _{BR}	I _T = 1mA, Pin 1 or Pin 2 to Pin 3	6			V
Reverse leakage current	I _R	V _{RWM} = 5V, Pin 1 or Pin 2 to Pin 3			0.2	μA
Forward Voltage	V _F	I _F = 10mA, Pin 3 to Pin 1 or Pin 2	0.5		1	V
Clamping Voltage	V _C	I _{PP} = 1A (tp = 8/20μs), Pin 1 or Pin 2 to Pin 3			9	V
Clamping Voltage	V _C	I _{PP} = 5A (tp = 8/20μs), Pin 1 or Pin 2 to Pin 3			11	V
Junction capacitance	C _J	V _R = 0V, f = 1MHz, Pin 1 to Pin 2		0.25		pF
Junction capacitance	C _J	V _R = 0V, f = 1MHz, Pin 1 or Pin 2 to Pin 3		0.5	0.8	pF

Typical Performance Characteristics ($T_A = 25^\circ\text{C}$ Unless otherwise noted)

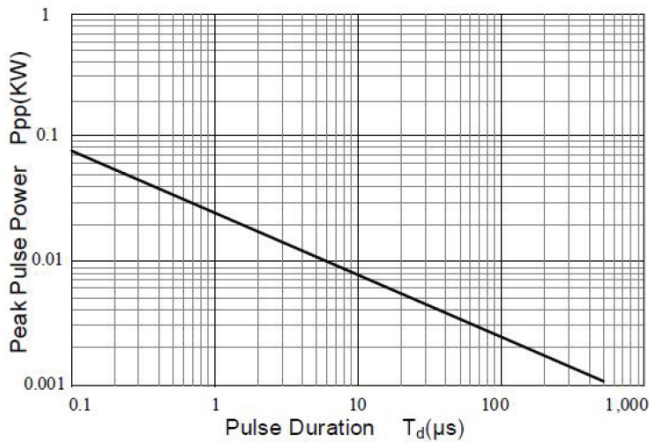


Fig 1. Peak Pulse Power vs. Pulse Time

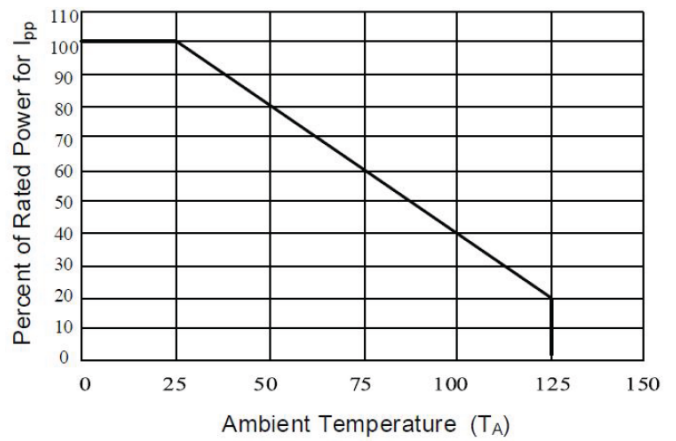


Fig 2. Power Derating Curve

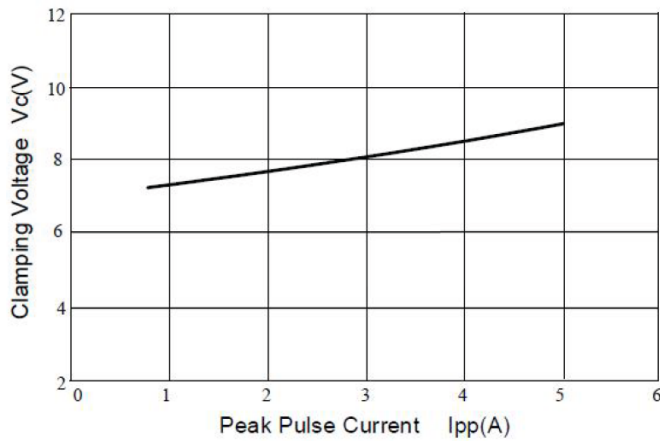


Fig 3. Clamping Voltage vs. Peak Pulse Current

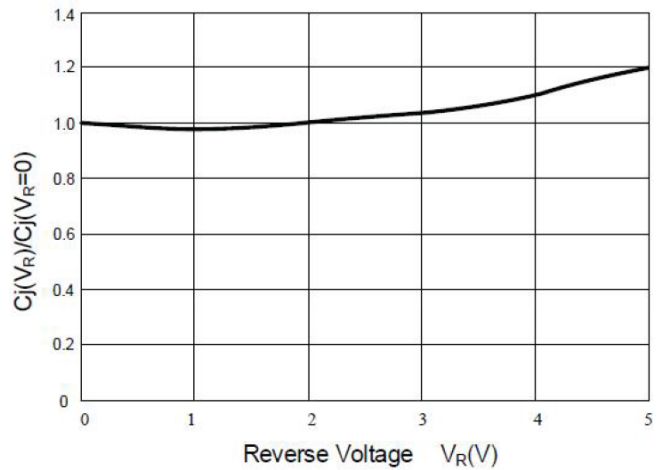


Fig 4. Junction Capacitance vs. Reverse Voltage

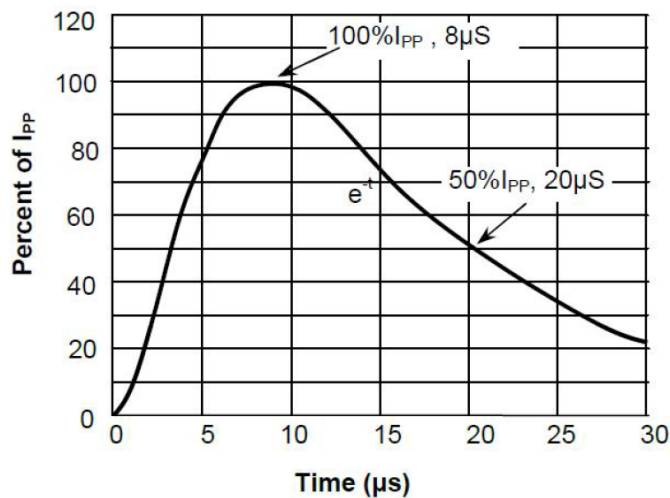


Fig 5. 8/20μs Pulse Waveform

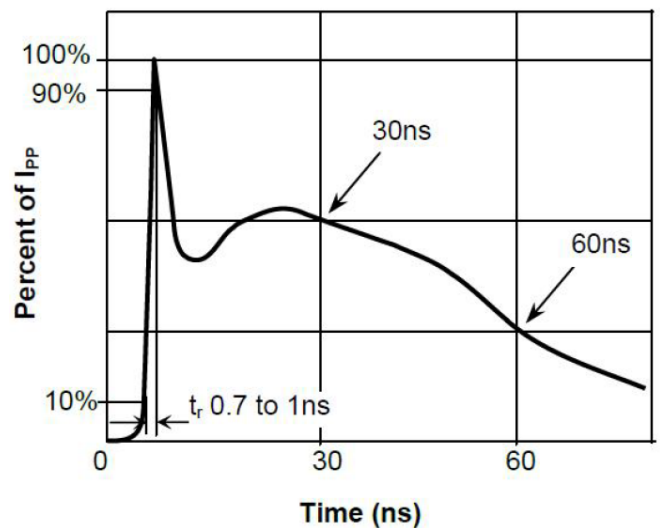
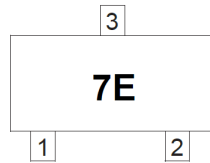


Fig 6. ESD(IEC 61000-4-2)Pulse Waveform

Suggested PAD Layout

Symbol	SOT-723	
	(mm)	(inch)
A	0.42	0.017
B	0.30	0.012
C	0.30	0.012
D	0.32	0.013
E	0.80	0.031
F	1.00	0.039

Marking Information



7E = Device Marking Code

Ordering information

Part Number	Package	Base qty	Reel Size	Delivery mode
		(pcs)	(inch)	
SC05L2UTM	SOT-723	3,000	7	Tape and reel